


PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCN No.	EMBEDDED PROCESSING/26/16131	
1.3 Title of PCN	HHGrace Wuxi (China) additional source for STM32H562x/563x and STM32H573x in E40 technology.	
1.4 Product Category	STM32H562x, STM32H563x and STM32H573x	
1.5 Issue date	2026-03-26	

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	
2.1.2 Phone	
2.1.3 Email	
2.2 Change responsibility	
2.2.1 Product Manager	
2.1.2 Marketing Manager	
2.1.3 Quality Manager	

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Transfer	Line transfer for a full process or process brick (process step, control plan, recipes) from one site to another site: Assembly site (SOP 2617)	HHGrace Wuxi (China)

4. Description of change

	Old	New
4.1 Description	Front-end sources for STM32H562x, STM32H563x and STM32H573x - ST CROLLES 300 (France)	Front-end sources for STM32H562x, STM32H563x and STM32H573x - ST CROLLES 300 (France) existing source - HHGrace (China) additional source
4.2 Anticipated Impact on form, fit, function, quality, reliability or processability?	No change	

5. Reason / motivation for change

5.1 Motivation	Second source introduction
5.2 Customer Benefit	CAPACITY INCREASE

6. Marking of parts / traceability of change

6.1 Description	Change is visible in the marking. Please refer to PCN 16131_Additional information.pdf document for further details.
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7. Timing / schedule

7.1 Date of qualification results	2026-07-10
7.2 Intended start of delivery	2026-07-15
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description	16131 MDRF-GPAM-RER2609 PCN16131 - HHGrace Wuxi (China) E40 - PLAN.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2026-03-26

9. Attachments (additional documentations)

16131 Public product.pdf
 16131 MDRF-GPAM-RER2609 PCN16131 - HHGrace Wuxi (China) E40 - PLAN.pdf
 16131 _Additional information.pdf

10. Affected parts

10. Affected parts		
10.1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STM32H562AGI7	
	STM32H562IGK6	
	STM32H562IGT6	
	STM32H562RGT6	
	STM32H562RGT6TR	
	STM32H562RGV6	
	STM32H562RIV6	
	STM32H562VGT6	
	STM32H562VGT6TR	
	STM32H562VIT6	
	STM32H562ZGT6	
	STM32H562ZIT6	
	STM32H563AII3Q	
	STM32H563IIK6	
	STM32H563IIK6TR	
	STM32H563RGT6	
	STM32H563RGV6	
	STM32H563RIT6	
	STM32H563RIV6	
	STM32H563VGT6	
	STM32H563VGT6TR	
	STM32H563VIT3Q	
	STM32H563VIT6	
	STM32H563VIT6TR	
	STM32H563ZGT6	
	STM32H563ZGT6TR	
	STM32H563ZGT7TR	
	STM32H563ZIT6	
	STM32H573IIK3Q	
	STM32H573IIK3QTR	
	STM32H573IIK6	
	STM32H573IIK6TR	
	STM32H573RIT6	
	STM32H573RIV6	
	STM32H573VIT6	
	STM32H573VIT6TR	
	STM32H573VIT7	
	STM32H573ZIT6	
	STM32H573ZIT6TR	

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**PRODUCT/PROCESS
CHANGE NOTIFICATION
PCN16131
– Additional information**

**HHGrace Wuxi (China) additional source for STM32H562x/563x
and STM32H573x in M40 technology.**

**MRDF - General Purpose and Automotive Microcontroller Division
(GPAM)**

What are the changes?

ST General Purpose Microcontrollers Division decided to qualify an additional front-end diffusion site. The full process will be transferred to HHgrace diffusion site maintaining state-of-the-art service level to our customers thanks to extra capacity. This PCN is limited to STM32H562x/563x and STM32H573x listed products as shown in tables below.

- The design database remains the same. No change in the silicon cut version.

How can the change be seen?

Changes are described in table below:

Table_1	Current condition	New condition
Front-End diffusion site	ST Crolles 300 (France)	HHGrace (China)
STM32H5x	STM32H562x/563x and STM32H573x cut 1.4	
Die revision Marking R	“W”	“4”
Diffusion plant code WX	“VQ”	“2E”



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How can the change be seen?

Package techno	Marking examples
LQFP 64 10x10 (5W)	<p>STM32H562RIT6 PP LLL WX R COO TF YWW ● SS</p>
LQFP 100 14x14 (1L)	<p>STM32H563VIT 7 PP LLL WX R COO TF YWW ● SS</p>
LQFP 144 20x20 (1A)	<p>STM32H563ZGT6 PP LLL WX R COO TF YWW ● SS ●</p>
LQFP 176 24x24 (1T)	<p>STM32H562IIT6 PP LLL WX R COO TF YWW SS ● ●</p>
TFBGA 13X13 225L (B04V)	<p>STM32H573LIH 3Q PP LLL WX R COO TF YWW ● SS</p>
UFBGA 10X10 176+25 (A0E7)	<p>STM32H563IGK 7 PP LLL WX R COO TF YWW ● SS</p>
UFBGA 7X7 169L (A0YV)	<p>STM32H5 62AG7 PP LLL WX R COO TF YWW ● SS</p>
VFQFPN 8X8 68L (B029)	<p>STM32H563 RGV6 PP LLL WX R COO TF YWW ● SS</p>
WLCSP 80 (B0D4)	<p>573MI3Q PP LLL WX COOYWWR</p>

Y WW indicates **Year Week code** (manufacturing date)

PP indicates **assembly traceability plant code**.

R indicates **Die Revision code**: change from **W** (ST Crolles 300) to **4** (HHGrace China).

WX indicates **Diffusion traceability plant code**: transferred from **VQ** (ST Crolles 300) to **2E** (HHGrace China Fab9).



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How to order samples?

For all samples request linked to this PCN, please:

- place a **Non-standard** sample order (choose Sample Non Std Type from pull down menu)
- insert the PCN number "**PCN16131**" into the NPO Electronic Sheet/**Regional Sheet**
- request sample(s) through Notice tool, indicating a single Commercial Product for each request

Partial Ship: 01 Price Pol: 05 Status: 01 Canc:

Sample Type: Sample Non Std Type

Closing Type: Sample Std Type
Sample Non Std Type
Sample Non Std w Spl Tests

Lab Sheet:

SO | NPO Sample

Header
SO Nr: 8018502433 Customer: 99770200 01 ST-TOKYO SO Type: 30 Sample Order Cost Center: JT3129 SAMPLES /SALES J
PO Nr: Carrier Code: 0001 Price Policy: 05 Currency: 02 U.S. DOLLAR Req Name:
Notes: Status: 01 All items pending.ri Issuing Date: 25-JUN-2018 Ord Val: 0.0000 Sample Req Date: 25-Jun-2018

Sch I Nr	PO I. Nr.	Finished Good	Comm Qty	Open Qty	Plant Open Qty	Reqd Qty	Unit Price	RD	CD	EDD	St
1.1.10	000001	STM32F429NIH6	30	30	30	30	0.0000	25-Jun-18	01-Mar-59	01-Mar-59	01

Final Cust:
PO Item: 000001 Comm Prod: STM32F429NIH6 Qty: 30 RD: 25-Jun-18 Unit Price: 0.0000 Final Cust: 8800367006 SANSHIN/NPC

Cust Part Nr: Finished Good: Partial Ship: 01 Price Pol: 05 Status: 01 Canc:

Notes: TAM K Pieces: 0 Our Share%: 0 Sample Type: Sample Non Std Type

Project Name: Closing Date: Closing Type:

Regional Sheet: Lab Sheet:

PCN16131



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MDRF-GPAM-RER2609 for PCN16131

**HHGrace Wuxi (China) additional source for
STM32H562x/563x and STM32H573x in E40 technology**

Reliability Evaluation Plan

18th March, 2026

MDRF GPAM Quality & Reliability Department

MDRF-GPAM-RER2609

HHGrace Wuxi (China) additional source in E40 technology

Die Test Vehicle

Package line	Assembly Line	Package	Device (RawLine Code)	Diffusion Process Plant	Number of Reliability Lots
BGA	JSCC	UFBGA 10x10 176+25L	MR*484	HHG E40	3

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Die Reliability Trials

Reliability Trial & Standard		Test Conditions	Pass Criteria	Units per Lot	Lot qty
HTOL	JESD22-A108	125°C & 3.6V 1200h	A0R1	77	3
EDR	JESD22-A117	125°C & 3.6V 100k cycles (*) + bake 150°C 1500h	A0R1	77	3
EDR	JESD22-A117	25°C & 3.6V 100k cycles + bake 150°C 168h	A0R1	77	3
EDR	JESD22-A117	-40°C & 3.6V 100k cycles + bake 150°C 168h	A0R1	77	3
LU	JESD78	125°C	A0R1	3	3
ESD HBM	JESD22-A114/C101	25°C 2kV, class 2	A0R1	3	3
ELFR	JESD22-A108 JESD74	125°C & 3.6V 48h	A0R1	800	3

(*) 100k cycles on 2*64 Kbytes & 10k cycles on other parts of memory

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HHGrace Wuxi (China) additional source in E40 technology

Package Test Vehicles

Package line	Back-End Plant	Package	Device (RawLine Code)	Option	Diffusion Process Plant	Number of Reliability Lots
BGA	JSCC	UFBGA 10x10 176+25L	MR*484	LDO	HHG E40	3
BGA	ASEKH	UFBGA 10x10 176+25L	MR*484	LDO		1
BGA	JSCC	TFBGA 13x13 225L	IB*484	SMPS		1
QFN	JSCC	VFQFPN 8x8 64L	GB*484	LDO		1
WLCSP	ASEKH	WLCSP 80L	3Y*484	SMPS		1
WLCSP	JCAP	WLCSP 80L	3Y*484	SMPS		1

Reliability strategy:

- Package reliability evaluations of HHG will be performed on 3 different assembly lots and 3 different wafer diffusion lots of die 484 in UFBGA 10x10 from JSCC with copper wires. This exercise will fully address package-oriented evaluations.
- Package reliability will be performed on 1 lot per assembly line to qualify 484 in ASEKH BGA/WLCSP, JSCC TFBGA/QFN and JCAP WLCSP assembly lines.
- ASEKH LQFP7x7 to 20x20 and LQFP24x24 are qualified by similarity with die 450 in HHG (refer RER n° MDG-GPM-RER2304)
- Refer to details in above and next tables.

MDRF-GPAM-RER2609

HHGrace Wuxi (China) additional source in E40 technology

Package Reliability Trials

Reliability Trial & Standard		Test Conditions	Pass Criteria	Unit per Lot	Lot qty
PC (BGA & QFN)	Pre Conditioning: Moisture Sensitivity Jedec Level 3 J-STD-020/ JESD22-A113	Bake (125°C / 24 hrs) Soak (30°C / 60% RH / 192 hrs) for level 3 Convection reflow: 3 passes	3 passes	231	6
PC (WLCSP)	Pre Conditioning: Moisture Sensitivity Jedec Level 1 J-STD-020/ JESD22-A113	Bake (125°C / 24 hrs) Soak (85°C / 85% RH / 168 hrs) for level 1 Convection reflow: 3 passes	3 passes	231	2
Uhast(*)	UnBiased Highly Accelerated Temperature and Humidity Stress JESD22 A118	130°C, 85%RH, 2.3 atm	96h	77	8
TC(*)	Thermal Cycling JESD22 A104	-65°C +150°C	500cy	77	8
THB(*)	Biased temperature & humidity stress JESD22 A101	85°C, 85% RH bias	1000h	77	8
HTSL	High Temperature Storage Life JESD22 A103	150°C- no bias	1000h	77	8
Construction analysis	JESDB100/B108 ST internal specifications	Construction analysis including physical dimensions measurement, Ball shear, pull test	NA	50	6
ESD	ESD Charge Device Model JEDEC JS-002	Aligned with device datasheet	Aligned with device datasheet	3	6

(*) tests performed after preconditioning

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PCN Title : HHGrace Wuxi (China) additional source for STM32H562x/563x and STM32H573x in E40 technology.

PCN Reference : EMBEDDED PROCESSING/26/16131

Subject : Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

STM32H563VIT6	STM32H562IGT6	STM32H562IGK6
STM32H563ZIT3QTR	STM32H563ZGT7	STM32H562RIV6
STM32H562AII6	STM32H563LIH3QTR	STM32H573ZIT6
STM32H573ZIT3Q	STM32H563VIT7TR	STM32H562IIK6
STM32H563VGT6	STM32H573RIV6	STM32H562VGT7
STM32H563MIY3QTR	STM32H573IIK3QTR	STM32H562IIT6
STM32H562RGT6	STM32H563VGT7TR	STM32H562AGI7
STM32H563ZGT6TR	STM32H573ZIT7	STM32H562ZIT6
STM32H563ZIT6	STM32H562RGV6	STM32H562VGT6
STM32H573VIT6TR	STM32H562ZGT6	STM32H573MIY3QTR
STM32H562ZGT6TR	STM32H562VIT6	STM32H563ZIT3Q
STM32H563VIT6TR	STM32H573LIH3QTR	STM32H573VIT6
STM32H563RIT6	STM32H563VGT6TR	STM32H562RIT6
STM32H563VIT3Q	STM32H563RIV6	STM32H563RGV6
STM32H563AII3Q	STM32H573RIT6	STM32H573IIT6
STM32H573IIT3Q	STM32H563IIT3Q	STM32H562VGT6TR
STM32H573VIT3Q	STM32H562RGT6TR	STM32H563ZGT7TR
STM32H563IIK3Q	STM32H563IGK6	STM32H573ZIT6TR
STM32H573ZIT3QTR	STM32H562AGI6	STM32H573AII6
STM32H563AII6	STM32H573IIK3Q	STM32H563IGT6
STM32H573VIT7	STM32H563ZGT6	STM32H563AGI6
STM32H563IIT6	STM32H573IIK6	STM32H563RIT7
STM32H563RGT6	STM32H563LIH3Q	STM32H563IGK7
STM32H563VIT7	STM32H573LIH3Q	STM32H573IIK6TR
STM32H563IIK6	STM32H563IIK6TR	STM32H562AGI7TR
STM32H573AII3Q		

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